

**TOREX SEMICONDUCTOR LTD.**  
Quality Assurance Dept.

## Composition Table

Product(Pb-free): XC9272xxxx4R-G  
Typical Mass: 4 mg

Part name	Weight(mg)	Material name	Ratio(ppm)	CAS number
Silicon chip	0.090	Silicon	22400	7440-21-3
		- Arsenic	<1	7440-38-2
Lead pad	1.255	Nickel	313900	7440-02-0
		Silver	29100	7440-22-4
		Gold	5600	7440-57-5
Die attach	0.026	Epoxy Resin	6600	—
		Acrylic Resin	3900	—
Bonding wire	0.095	Gold	23600	7440-57-5
Resin	1.846	Silica	461400	60676-86-0
		Epoxy Resin	46800	—
		Phenol Resin	44000	—
		Metal hydroxide	42700	—

\* The component composition is based on the information provided by raw material vender.

\* The mass of the IC and its fractions could be different due to the manufacturing conditions of materials.

\* Any indication "-" in CAS number means "confidential."